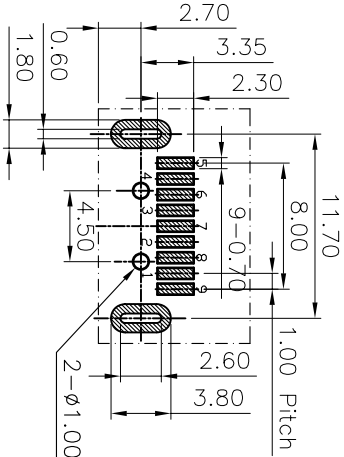
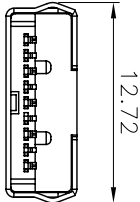
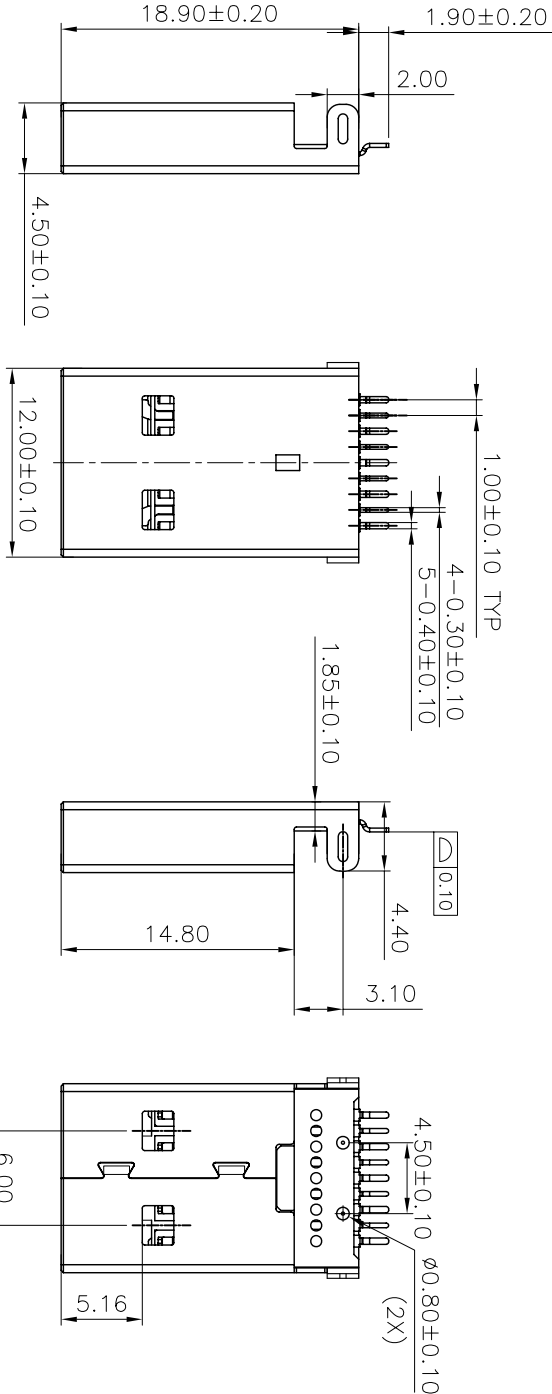


REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	ECN120306011	新发行	xu dong bin	—	—	12-03-06
A1	ECN130801001	变更料号	WEI			13-08-01

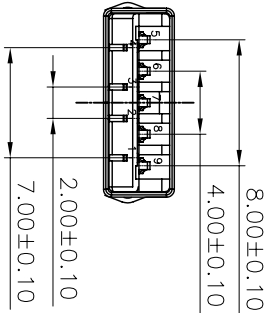


REFERENCE PCB LAYOUT



料号备注:
CU3M002MXXTXXR

"12"半宽锡膏G/F
"15"半宽锡膏15U"
"16"半宽锡膏30U"



PIN NUMBER	SIGNAL NAME	UNLESS OTHERWISE SPECIFIED TOLERANCES	APPROVAL	日期	品名规格	USB AM 3.0 SMT L=1.9 K脚
1	VBUS		制图 WEIMINGJUN	2012.03.06		
2	D-		审核 xudongbin	2012.03.06		
3	D+		核准 xudongbin	2012.03.06		
4	GND					
5	Stda_SSRX-	X, +/-				
6	Stda_SSRX+	X, +/-				
7	GND_DRAIN	XX +/-				
8	Stda_SSTX-	ANGLES +/-				
9	Stda_SSTX+	DIMENSIONS				
	Shell(Shield)	(METRIC) (MM)				

SPECIFICATIONS:
Contact current Rating:
1.8 Amperes for pin1&pin4,
0.25 Amperes other contacts
Dielectric Withstanding Voltage:AC 100V(RMS)
Insulation resistance:100Megohms Minimum.
Contact Resistance:
30mΩ Max for pin1&pin4
50mΩMax for other contacts
Mechanical Characteristics:
Mating Force:35 Newtons,Maximum
Unmating Force:10 Newtons,Minimum.
MATERIAL:
Housing: LCP+30%GF 94V-0 COLOR:BLUE
Contact: copper alloy(T=0.25mm)
PLATING:
Spell: SPC
Contact: Au Plated on contact area
Tin Plated on solder area
Nickel Underplating over all
operating Temperature:-55°to+85°